

ABSTRACT OF THE DISCLOSURE

Process solutions comprising one or more surfactants are used to reduce the
5 number of defects in the manufacture of semiconductor devices. In certain preferred
embodiments, the process solution of the present invention may reduce post-
development defects such as pattern collapse when employed as a rinse solution either
during or after the development of the patterned photoresist layer. Also disclosed is a
method for reducing the number of pattern collapse defects on a plurality of photoresist
10 coated substrates employing the process solution of the present invention.